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REGULAR PAPERS

Advanced Packaging Technologies

Sintered-Silver Bonding of High-Temperature Piezoelectric Ceramic Sensors	3
..... J. Billore, S. Hascoët, R. Robutel, C. Buttay, and J. Li	
Novel Silver Solid-State Bonding Designs Between Two Copper Structures	10
..... Y.-L. Chen and C. C. Lee	
Solid-State-Diffusion Bonding for Wafer-Level Fine-Pitch Cu/Sn/Cu Interconnect in 3-D Integration	19
..... J. Wang, Q. Wang, Z. Wu, D. Wang, and J. Cai	
Contact Resistance of Microbumps in a Typical Through-Silicon-Via Structure	27
..... B.-J. Lwo, C.-L. Teng, K.-F. Tseng, T. Ni, and S. Lu	
3-D TSV Six-Die Stacking and Reliability Assessment of 20- μ m-Pitch Bumps on Large-Scale Dies	33
..... J. B. Lee, J. L. Aw, and M. W. Rhee	
Volterra Series-Based Time-Domain Macromodeling of Nonlinear Circuits	39
..... X. Y. Z. Xiong, L. J. Jiang, J. E. Schutt-Ainé, and W. C. Chew	

Components: Characterization and Modeling

Si-Based Hybrid Microcooler With Multiple Drainage Microtrenches for High Heat Flux Cooling	50
..... Y. Han, B. L. Lau, G. Tang, X. Zhang, and D. M. W. Rhee	
Fast Nonlinear Dynamic Compact Thermal Modeling With Multiple Heat Sources in Ultra-Thin Chip Stacking Technology	58
..... L. Codecasa, V. d'Alessandro, A. Magnani, and N. Rinaldi	

Electrical Performance of Integrated Systems

A Fully 3-D Printed Waveguide and Its Application as Microfluidically Controlled Waveguide Switch	70
..... S. Khan, N. Vahabisani, and M. Daneshmand	
Waveguide-Stripline Series-Corporate Hybrid Feed Technique for Dual-Polarized Antenna Array Applications	81
..... G.-L. Huang, S.-G. Zhou, T.-H. Chio, C.-Y.-D. Sim, and T.-S. Yeo	
A Novel Multilayer Electromagnetic Bandgap Structure Composed of Square Rings as Microwave Guiding Structures	88
..... H. Ouassal, J. Shaker, L. Roy, M. R. Chaharmir, and K. Hettak	
Single-Filter Structure With Tunable Operating Frequency in Noncontiguous Bands	98
..... B. Lee, S. Nam, T.-H. Lee, C.-S. Ahn, and J. Lee	

(Contents Continued on Page 2)

(Contents Continued from Page 1)

Design of SIW-Based Multi-Aperture Couplers Using Ray Tracing Method	<i>Z. Liu and G. Xiao</i>	106
A Hybrid Integrated High-Gain Antenna With an On-Chip Radiator Backed by Off-Chip Ground for System-on-Chip Applications	<i>Y. Song, K. Kang, Y. Tian, Y. Wu, Z. Li, Y. Guo, Y. Ban, J. Liu, X. Tang, H. Liu, and J. Yang</i>	114
A Universal Reference Line-Based Differential Phase Shifter Structure With Simple Design Formulas	<i>B. W. Xu, S. Y. Zheng, Y. M. Pan, and Y. H. Huang</i>	123
<i>Electronics Manufacturing</i>		
An Integrated Approach for Via Metallization in Microwave Substrates	<i>S. N. Bhat, J. Varghese, and S. V. Sharma</i>	131
Through Silicon Via (TSV) Defect Modeling, Measurement, and Analysis	<i>D. H. Jung, Y. Kim, J. J. Kim, H. Kim, S. Choi, Y.-H. Song, H.-C. Bae, K.-S. Choi, S. Piersanti, F. de Paulis, A. Orlandi, and J. Kim</i>	138
The Bonding Forming Simulation and Reliability Research of the Flip-Chip Stacked Gold Stud Bump	<i>C. Huang, W. Tang, and L. Zhang</i>	153
